

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IDB18E120	**Issued**	27. April 2022
MA#	MA005734948		
Package	PG-TO263-3-2	**Weight***	1558.85 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.293	0.21	0.21	2112	2112
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.50	19.53	195032	195286
wire	non noble metal	aluminium	7429-90-5	3.313	0.21	0.21	2126	2126
encapsulation	inorganic material	zincoxide	1314-13-2	6.868	0.44		4406	
	miscellaneous	miscellaneous	-	27.472	1.76		17624	
	plastics	epoxy resin	-	103.022	6.61		66088	
	inorganic material	silicondioxide	60676-86-0	549.449	35.26	44.07	352470	440588
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6195	6195
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	147	148
solder	non noble metal	tin	7440-31-5	0.055			35	
	noble metal	silver	7440-22-4	0.069			44	
	non noble metal	lead	7439-92-1	2.621	0.17	0.17	1681	1760
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		106	
	non noble metal	iron	7439-89-6	0.548	0.04		352	
	non noble metal	copper	7440-50-8	547.666	35.13	35.18	351327	351785
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com